

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TDA21472	**Issued**	12. December 2019
MA#	MA005410694		
Package	PG-IQFN-39-2	**Weight***	111.42 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.261	0.23	0.23	2347	2347
chip_2	inorganic material	silicon	7440-21-3	0.966	0.87	0.87	8669	8669
chip_3	inorganic material	silicon	7440-21-3	1.538	1.38	1.38	13806	13806
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		103	
	non noble metal	zinc	7440-66-6	0.046	0.04		411	
	non noble metal	iron	7439-89-6	0.917	0.82		8227	
	non noble metal	copper	7440-50-8	37.219	33.41	34.28	334040	342781
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		745	
	plastics	epoxy resin	-	4.278	3.84		38392	
	inorganic material	silicondioxide	60676-86-0	37.170	33.36	37.27	333599	372736
leadfinish	noble metal	palladium	7440-05-3	0.000	0.00		2	
	noble metal	gold	7440-57-5	0.000	0.00		4	
	non noble metal	nickel	7440-02-0	0.007	0.01	0.01	65	71
plating	noble metal	silver	7440-22-4	0.967	0.87	0.87	8677	8677
solder	non noble metal	tin	7440-31-5	0.036	0.03		326	
	noble metal	silver	7440-22-4	0.045	0.04		408	
	non noble metal	lead	7439-92-1	1.735	1.56	1.63	15573	16307
heat sink clip	inorganic material	phosphorus	7723-14-0	0.008	0.01		70	
	non noble metal	iron	7439-89-6	0.026	0.02		235	
	non noble metal	copper	7440-50-8	26.106	23.43	23.46	234301	234606
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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